

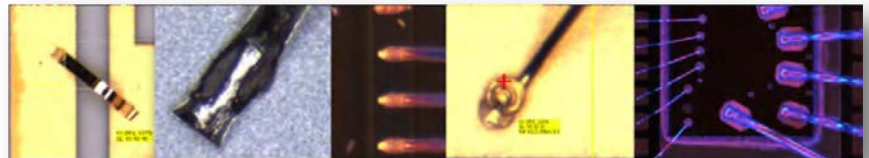
The Full Spectrum of AOI Solutions

Cleanroom Configuration for Microelectronics - MVP 850 CL

The MVP 850 CL AOI is designed for Cleanroom Operation. Ideal for Laminar Flow environments the 850 CL is open top and designed to allow laminar air flow through the machine body. The 850 CL is capable to operate in cleanrooms down to Class 100. The 850 CL can be configured for inline operation or as required with a single MVP integrated loader module. For the integrated loader module MVP can handle both Waffle and Jedec Trays. Defect handling option such as Wire Cutting/Ripping and Ink Marking are available as options for the DWMS model as well as provision of XML defect maps.

Key features and inspection capabilities:

- Class 100 Cleanroom Capable**
- Inline or Integrated Single Loader/Unloader Unit**
- Multiple Defect Identification Options**
- Wire Rip, Ink Mark, XML Mapping**
- Au, Al, Ag, and Cu Wires**
- Wedge, Ball, and Stitch Bonds**
- Crescent, and Tape Bonds**
- Epoxy Flow and Spread**
- Die Placement, Surface and Edge Damage**
- Foreign Objects and Scratches**
- SMT Components**



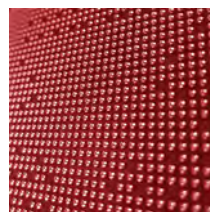
Discuss your SMT and microelectronics inspection application with Machine Vision Products, Inc and discover your solution



SMT AOI



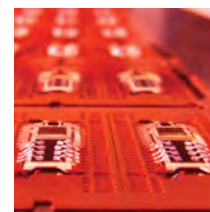
3D Paste AOI



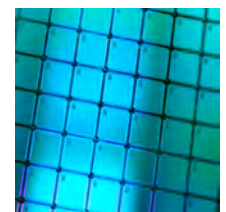
BGA AOI



Wire Bond AOI



Die and Epoxy AOI



Die Surface AOI



Key Capabilities

Inspection Capabilities

The MVP 850 CL, when configured for Die, Wire-Bond and Lead-Frame inspection provides capabilities for:

Using three standard options (between 1 and 6um resolution)

- Au, Al, Ag, and Cu Wires
- Wedge, Ball, and Stitch Bonds
- Crescent, and Tape Bonds
- Bond Layer
- Epoxy Flow and Spread
- Die Placement
- Die Surface
- Edge Damage
- SMT Components

Manufacturing Deployment

Post Die Bonder

- Die Surface Inspection
- Die Position (DPMS)
- Bond Layer Thickness (BLT)
- Lead Frame Inspection
- Epoxy Inspection

Post Wire Bonder

- Wire Inspection (Au, Al, Cu and Ag)
- Lead Frame Inspection
- Die Surface Inspection
- Die Position (DPMS)
- Coating

Final Packaging

- Coplanarity
- Lead Inspection
- Markings
- Surface Inspection

Measurement Approach

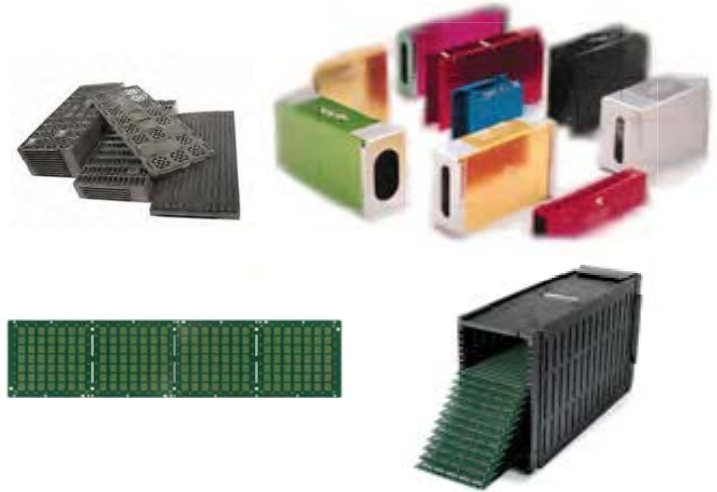
The 850 CL Microelectronics Inspection System provides both 2D and 3D measurements through the use of its proprietary Optics and 3D Laser based measurement system.

Handling Options

MVP 850 CL can be configured for multiple handling solutions which include:

Lot Solutions

- Magazine Lifters/Indexers
- Wafer Handling
- JEDEC Tray Handling
- Waffle Packs
- Other Customized Handling



Software Features

All algorithms and measurement techniques provide for full Wire-bond, Die, Surface and packaging inspection, Software Packages Include:

- ePro - Program set-up
- iRepair - Defect Map and review software
- Integrated Review for Increased Throughput
- Full Microelectronics algorithm suite
- Full AutoNetworker Support

Defect Marking Options

MVP provide multiple options for defect identification, which include:

- Electronic Mapping/SECS/GEM
- Wire Removal/Cutting
- Ink Marking
- Punching
- External and Custom Solutions

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